
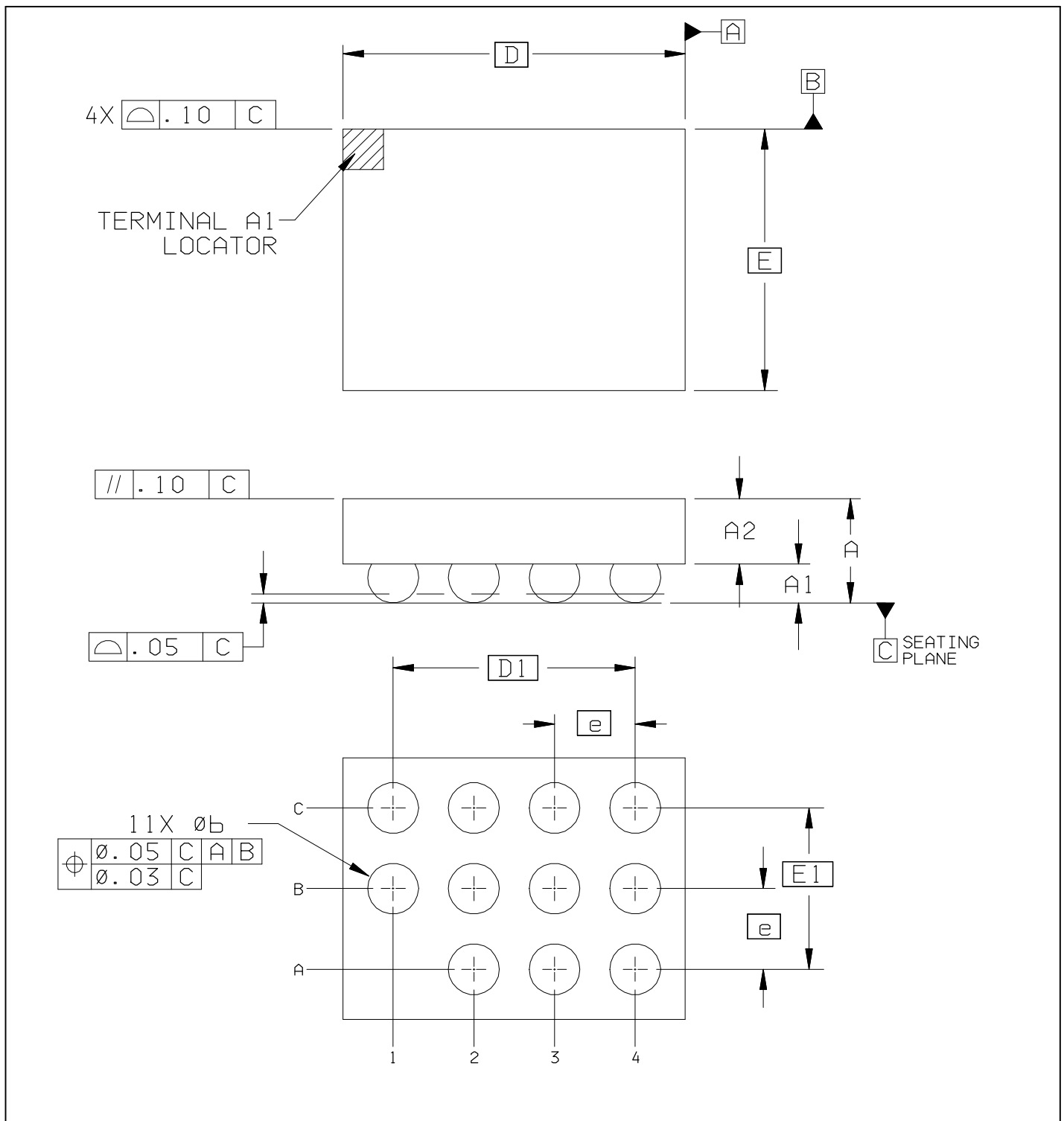



ON Semiconductor 	MECHANICAL OUTLINES DICTIONARY	98AON11554D	
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CASE NO.	499B-01
STATUS	ON SEMICONDUCTOR STANDARD
NEW STD	
USED ON	11 PIN FLIPCHIP CSP 2.12X1.62MM, 0.50MM PITCH



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NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. COPLANARITY APPLIES TO SPHERICAL CROWNS OF SOLDER BALLS.

DIM	MILLIMETERS		INCHES		DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
A	---	0.700							
A1	0.210	0.270							
A2	0.380	0.430							
D	2.120	BSC							
E	1.620	BSC							
b	0.290	0.340							
e	0.500	BSC							
D1	1.500	BSC							
E1	1.000	BSC							

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ISSUE	REVISION	COORD/ DATE
0	RELEASED FOR PRODUCTION. REQ BY K. KIME.	FB 29 May 2002